

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Features

- Lead free device (RoHS Compliant*)
- Protects 8 lines
- Unidirectional & bidirectional configurations
- ESD protection

Applications

- Audio/video inputs
- RS-232, RS-422 & RS-423 data lines
- Portable electronics
- Medical sensors

CDNBS16-T03~T36C - TVS Diode Array Series

General Information

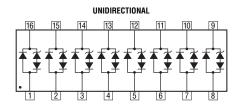
The markets of portable communications, computing and video equipment are challenging the semiconductor industry to develop increasingly smaller electronic components.

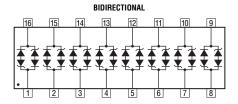
Bourns offers Transient Voltage Suppressor Array diodes for surge and ESD protection applications, in 16 Lead Narrow Body SOIC package size format. The Transient Voltage Suppressor Array series offer a choice of voltage types ranging from 3 V to 36 V in unidirectional and bidirectional configurations. Bourns® Chip Diodes conform to JEDEC standards, are easy to handle on standard pick and place equipment and their flat configuration minimizes roll away.

The Bourns® device will meet IEC 61000-4-2 (ESD), IEC 61000-4-4 (EFT) and IEC 61000-4-5 (Surge) requirements.

Thermal Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

Parameter	Symbol	Max.	Unit	
Operating Temperature	TJ	-55 to +150	°C	
Storage Temperature	Тѕтс	-55 to +150	°C	





Electrical Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

								CDN	BS16-							11.2
Parameter	Symbol	Uni-	Bi-	Uni-	Bi-	Uni-	Bi-	Uni-	Bi-	Uni-	Bi-	Uni-	Bi-	Uni-	Bi-	Unit
		T03	T03C	T05	T05C	T08	T08C	T12	T12C	T15	T15C	T24	T24C	T36	T36C	
Minimum Breakdown Voltage @ 1 mA	V _{BR}	4.5		6.0		8.5		13.3		16.7		26.7		40.0		V
Working Peak Voltage	V _{WM}	3.0		5.0		8.0		12.0		15.0		24.0		36.0		V
Maximum Clamping Voltage VC @ Ip = 1 A¹	Vc	8.0		9	9.8 13.4		3.4	19.0 25.5		40.0		53.0		V		
Maximum Clamping Voltage @ 8/20 µs VC @ Ipp¹	Vc	23 V 24 V @ 43 A @ 42			26 V @ 30 A		33 V 39 V @ 21 A @ 15 A		57 V @ 10 A		72 V @ 7 A		V			
Maximum Leakage Current @ V _{WM}	Ισ	1	125 20		1	10	2		2		2			2	μΑ	
Maximum Capacitance @ 0 V, 1 MHz	C _{j(SD)}		15								pF					
Temperature Coefficient of VBR		-	-3	3		9 16		17		2	26		36	mV/°C		
Peak Pulse Power (tp = 8/20 µs) ²	P _{PP}	500							W							
Forward Voltage @ 100 mA, 300 µs – Square Wave ³	VF	1.5						V								

Notes:

- 1. See Pulse Wave Form.
- 2. See Peak Pulse Power vs. Pulse Time.
- 3. Only applies to unidirectional devices.
- 4. Part numbers with a "C" suffix are bidirectional devices, i.e., CDNBS16-T03C.

CDNBS16-T03~T36C - TVS Diode Array Series

BOURNS®

Mechanical Characteristics

This is a molded JEDEC Narrow Body SO-16 package with lead free 100 % Sn plating on the lead frame. It weighs approximately 30 mg and has a flammability rating of UL 94V-0.

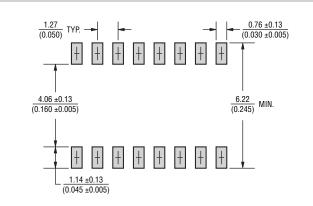
Product Dimensions 9.80 - 10.00 (0.386 - 0.393) 5.80 - 6.20 (0.150 - 0.157)(0.229 - 0.244)(0.05)(0.054 - 0.068)R x 45 ° 0.19 - 0.25(0.008 - 0.009)0.35 - 0.49 (0.014 - 0.019) 0.10 - 0.25 0.40 - 1.25 (0.004 - 0.009)(0.016 - 0.049)16 PLCS. DIMENSIONS = MILLIMETERS

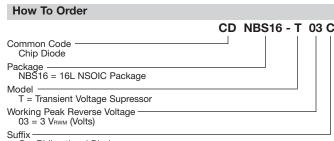
Typical Part Marking

CDNBS16-T12CDNBS16-T12 CDNBS16-T15CDNBS16-T15 CDNBS16-T36CDNBS16-T36 CDNBS16-T03CCDNBS16-T03C CDNBS16-T05CCDNBS16-T05C CDNBS16-T08CCDNBS16-T08C

CDNBS16-T36CCDNBS16-T36C

Recommended Footprint



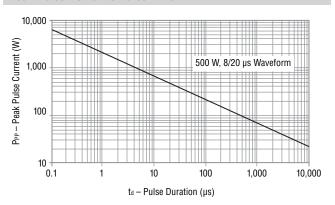


CDNBS16-T03~T36C - TVS Diode Array Series

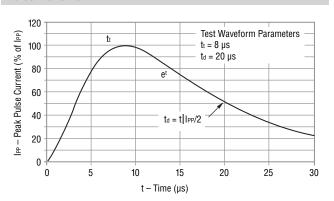
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Performance Graphs

Peak Pulse Power vs Pulse Time

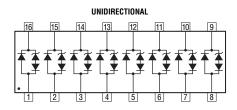


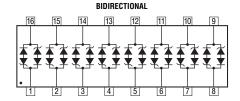
Pulse Wave Form



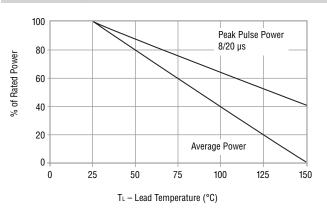
Block Diagram

The device block diagrams below include the pin names and basic electrical connections associated with each channel.





Power Derating Curve

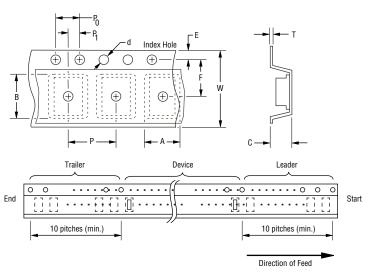


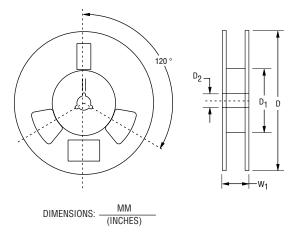
Device Pinout

Pin	Function	Pin	Function
1	GND	9	I/O 1
2	GND	10	I/O 2
3	GND	11	I/O 3
4	GND	12	I/O 4
5	GND	13	I/O 5
6	GND	14	I/O 6
7	GND	15	I/O 7
8	GND	16	I/O 8

Packaging Specifications

The product will be dispensed in Tape and Reel format (see diagram below).





Devices are packed in accordance with EIA standard RS-481-A.

[110010 401
Item	Symbol	NSOIC 16L
Carrier Width	А	$\frac{6.7 \pm 0.10}{(0.264 \pm 0.004)}$
Carrier Length	В	$\frac{10.5 \pm 0.10}{0.413 \pm 0.004}$
Carrier Depth	С	$\frac{2.10 \pm 0.10}{0.083 \pm 0.004}$
Sprocket Hole	d	$\frac{1.55 \pm 0.05}{(0.061 \pm 0.002)}$
Reel Outside Diameter	D	330 (12.992)
Reel Inner Diameter	D ₁	$\frac{80.0}{(3.1500)}$ MIN.
Feed Hole Diameter	D ₂	$\frac{13.0 \pm 0.20}{(0.512 \pm 0.008)}$
Sprocket Hole Position	Е	$\frac{1.75 \pm 0.10}{(0.069 \pm 0.004)}$
Punch Hole Position	F	$\frac{3.50 \pm 0.05}{(0.138 \pm 0.002)}$
Punch Hole Pitch	Р	$\frac{8.00 \pm 0.10}{(0.315 \pm 0.004)}$
Sprocket Hole Pitch	P ₀	$\frac{4.00 \pm 0.10}{(0.157 \pm 0.004)}$
Embossment Center	P ₁	$\frac{2.00 \pm 0.05}{(0.079 \pm 0.002)}$
Overall Tape Thickness	Т	$\frac{0.20 \pm 0.10}{(0.008 \pm 0.004)}$
Tape Width	W	$\frac{16.00 \pm 0.20}{(0.630 \pm 0.008)}$
Reel Width	W ₁	$\frac{18.4}{(0.724)}$ MAX.
Quantity per Reel	-	2500